

# MECHANICAL CASE OUTLINE

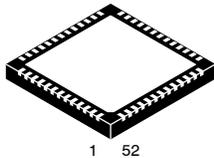
## PACKAGE DIMENSIONS

ON Semiconductor®

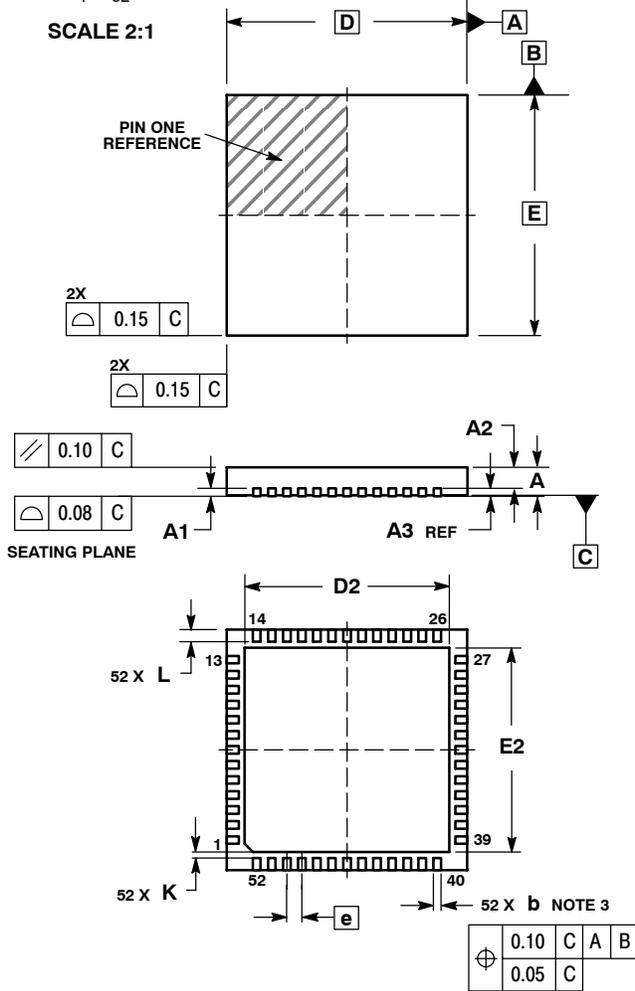


**QFN52 8x8, 0.5P**  
CASE 485M-01  
ISSUE C

DATE 16 FEB 2010



1 52  
SCALE 2:1

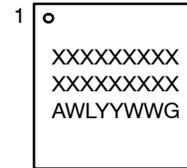


**NOTES:**

1. DIMENSIONING AND TOLERANCING PER ASME Y14.5M, 1994.
2. CONTROLLING DIMENSION: MILLIMETERS
3. DIMENSION b APPLIES TO PLATED TERMINAL AND IS MEASURED BETWEEN 0.25 AND 0.30 MM FROM TERMINAL.
4. COPLANARITY APPLIES TO THE EXPOSED PAD AS WELL AS THE TERMINALS.

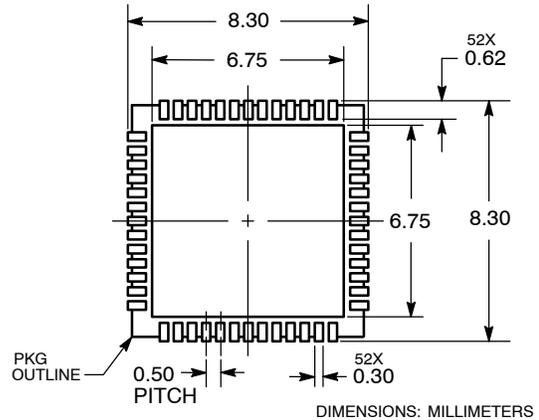
MILLIMETERS		
DIM	MIN	MAX
A	0.80	1.00
A1	0.00	0.05
A2	0.60	0.80
A3	0.20 REF	
b	0.18	0.30
D	8.00 BSC	
D2	6.50	6.80
E	8.00 BSC	
E2	6.50	6.80
e	0.50 BSC	
K	0.20	---
L	0.30	0.50

**GENERIC MARKING DIAGRAM**



- XXXXXXXXXX = Device Code
- A = Assembly Site
- WL = Wafer Lot
- YY = Year
- WW = Work Week
- G = Pb-Free Package

**RECOMMENDED SOLDERING FOOTPRINT**



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<b>STATUS:</b>	ON SEMICONDUCTOR STANDARD	
<b>NEW STANDARD:</b>		
<b>DESCRIPTION:</b>	52 PIN QFN, 8X8, 0.5P	<b>PAGE 1 OF 2</b>

